TOSHIBA

TOSHIBA Original CMOS 16-Bit Microcontroller

TLCS-900/L Series

TMP93PW40

TOSHIBA CORPORATION

Semiconductor Company

Preface

Thank you very much for making use of Toshiba microcomputer LSIs. Before use this LSI, refer the section, "Points of Note and Restrictions". Especially, take care below cautions.

CAUTION How to release the HALT mode

Usually, interrupts can release all halts status. However, the interrupts = (NMI, INT0), which can release the HALT mode may not be able to do so if they are input during the period CPU is shifting to the HALT mode (for about 3 clocks of f_{FPH}) with IDLE1 or STOP mode (IDLE2, RUN is not applicable to this case). (In this case, an interrupt request is kept on hold internally.)

If another interrupt is generated after it has shifted to HALT mode completely, halt status can be released without difficultly. The priority of this interrupt is compare with that of the interrupt kept on hold internally, and the interrupt with higher priority is handled first followed by the other interrupt.

Low Voltage/Low Power

CMOS 16-Bit Microcontrollers TMP93PW40DF

1. Outline and Device Characteristics

The TMP93PW40 is OTP type MCU which includes 128-Kbyte One-time PROM. Using the adapter-socket, you can write and verify the data for TMP93PW40.TMP93PW40 has the same pin-assignment with TMP93CW40 (Mask ROM type).

Writing the program to built-in PROM, the TMP93PW40 operates as the same way with TMP93CW40.

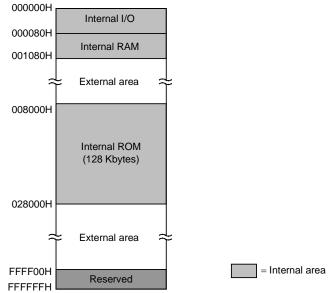


Figure 1.1 Memory Map of TMP93CW40/PW40

MCU	ROM	RAM	Package	Adapter Socket
TMP93PW40DF	OTP 128 Kbytes	4 Kbytes	P-LQFP100-1414-0.50F	BM11129

030619EBP1

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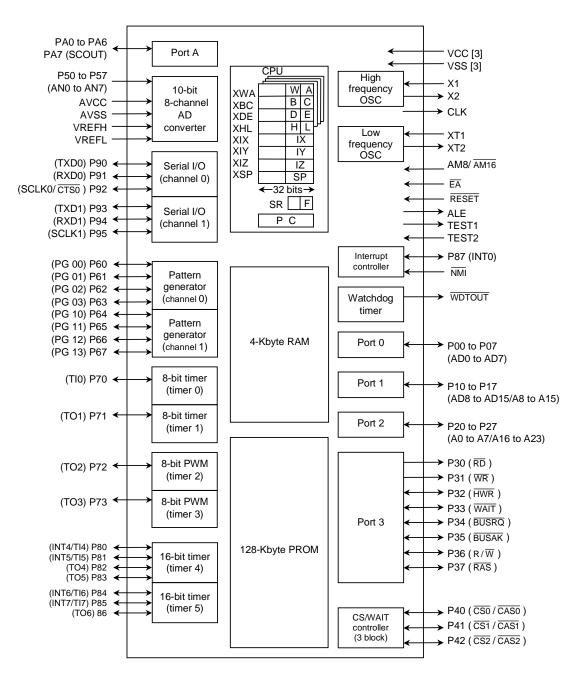


Figure 1.2 TMP93PW40 Block Diagram

2. Pin Assignment and Functions

The assignment of input/output pins for TMP93PW40, their name and outline functions are described below.

2.1 Pin Assignment

Figure 2.1.1 shows pin assignment of TMP93PW40.

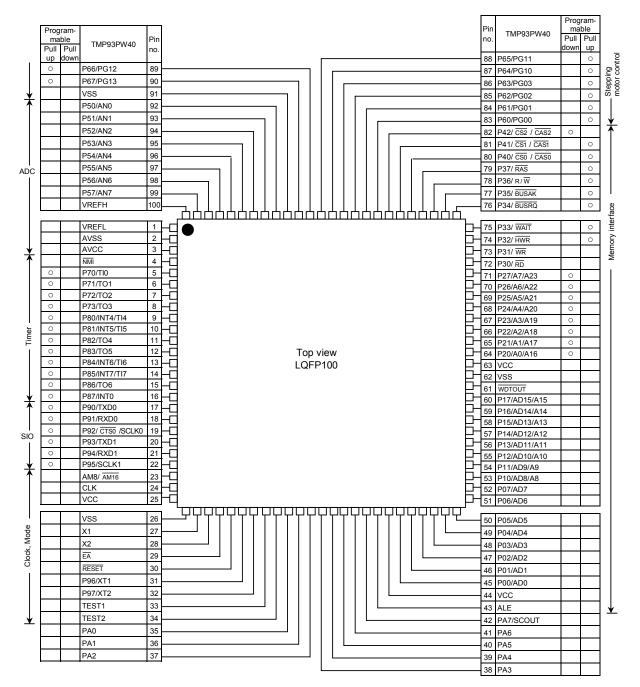


Figure 2.1.1 Pin Assignment (100-Pin LQFP)

2.2 Pin Names and Functions

The names of the input/output pins and their functions are described below. (1) Pin names and functions of TMP93PW40 in MCU mode. (Table 2.2.1 to Table 2.2.4)

Pin Names	Number of Pins	I/O	Functions
P00 to P07	8	I/O	Port 0: I/O port that allows I/O to be selected on a bit basis.
AD0 to AD7		3 state	Address/data (lower) : 0 to 7 for address/data bus.
P10 to P17	8	I/O	Port 1: I/O port that allows I/O to be selected on a bit basis.
AD8 to AD15		3 state	Address/data (upper): 8 to 15 for address/data bus.
A8 to A15		Output	Address: 8 to 15 for address bus.
P20 to P27	8	I/O	Port 2: I/O port that allows selection of I/O on a bit basis (with pull-down resistor).
A0 to A7		Output	Address: 0 to 7 for address bus.
A16 to A23		Output	Address: 16 to 23 for address bus.
P30	1	Output	Port 30: Output port.
RD		Output	Read: Strobe signal for reading external memory.
P31	1	Output	Port 31: Output port.
WR		Output	Write: Strobe signal for writing data on pins AD0 to AD7.
P32	1	I/O	Port 32: I/O port (with pull-up resistor).
HWR		Output	High write: Strobe signal for writing data on pins AD8 to AD15.
P33	1	I/O	Port 33: I/O port (with pull-up resistor).
WAIT		Input	Wait: Pin used to request CPU bus wait.
P34	1	I/O	Port 34: I/O port (with pull-up resistor).
BUSRQ		Input	Bus request: Signal used to request high impedance for AD0 to AD15, A0 to A23, \overline{RD} , \overline{WR} , \overline{HWR} , R/\overline{W} , \overline{RAS} , $\overline{CS0}$, $\overline{CS1}$, and $\overline{CS2}$ pins. (for external DMAC)
P35	1	I/O	Port 35: I/O port (with pull-up resistor).
BUSAK		Output	Bus acknowledge: Signal indicating that AD0 to AD15, A0 to A23, \overline{RD} , \overline{WR} , \overline{HWR} , R/\overline{W} , \overline{RAS} , $\overline{CS0}$, $\overline{CS1}$, and $\overline{CS2}$ pins are at high impedance after receiving BUSRQ. (for external DMAC)
P36	1	I/O	Port 36: I/O port (with pull-up resistor).
R/\overline{W}		Output	Read/write: 1 represents read or dummy cycle; 0, write cycle.
P37	1	I/O	Port 37: I/O port (with pull-up resistor).
RAS		Output	Row address strobe: Outputs RAS strobe for DRAM.
P40	1	I/O	Port 40: I/O port (with pull-up resistor).
CS0		Output	Chip select 0: Outputs 0 when address is within specified address area.
CAS0		Output	Column address strobe 0: Outputs \overline{CAS} strobe for DRAM when address is within specified address area.

Table 2.2.1 Names and Functions in MCU Mode (1/4)

Note: With the external DMA controller, this device's built-in memory or built-in I/O cannot be accessed using the BUSRQ and BUSAK pins.

Pin Names	Number of Pins	I/O	Functions
P41	1	I/O	Port 41: I/O port (with pull-up resistor).
CS1		Output	Chip select 1: Outputs 0 if address is within specified address area.
CAS1		Output	Column address strobe 1: Outputs \overline{CAS} strobe for DRAM if address is within specified address area.
P42	1	I/O	Port 42: I/O port (with pull-down resistor).
CS2		Output	Chip select 2: Outputs 0 if address is within specified address area.
CAS2		Output	Column address strobe 2: Outputs \overrightarrow{CAS} strobe for DRAM if address is within specified address area.
P50 to P57	8	Input	Port 5: Input port.
AN0 to AN7		Input	Analog input: Input to AD converter.
VREFH	1	Input	Pin for reference voltage input to AD converter (H).
VREFL	1	Input	Pin for reference voltage input to AD converter (L).
P60 to P63	4	I/O	Ports 60 to 63: I/O ports that allow selection of I/O on a bit basis
			(with pull-up resistor).
PG00 to PG03		Output	Pattern generator ports: 00 to 03.
P64 to P67	4	I/O	Ports 64 to 67: I/O ports that allow selection of I/O on a bit basis
			(with pull-up resistor).
PG10 to PG13		Output	Pattern generator ports: 10 to 13.
P70	1	I/O	Port 70: I/O port (with pull-up resistor).
T10		Input	Timer input 0: Timer 0 input.
P71	1	I/O	Port 71: I/O port (with pull-up resistor).
TO1		Output	Timer output 1: Timer 0 or 1 output.
P72	1	I/O	Port 72: I/O port (with pull-up resistor).
TO2		Output	PWM output 2: 8-bit PWM timer 2 output.
P73	1	I/O	Port 73: I/O port (with pull-up resistor).
TO3		Output	PWM output 3: 8-bit PWM timer 3 output.
P80	1	I/O	Port 80: I/O port (with pull-up resistor).
TI4		Input	Timer input 4: Timer 4 count/capture trigger signal input.
INT4		Input	Interrupt request pin 4: Interrupt request pin with programmable rising/falling edge.
P81	1	I/O	Port 81: I/O port (with pull-up resistor).
TI5		Input	Timer input 5: Timer 4 count/capture trigger signal input.
INT5		Input	Interrupt request pin 5: Interrupt request pin with rising edge.
P82	1	I/O	Port 82: I/O port (with pull-up resistor).
TO4		Output	Timer output 4: Timer 4 output pin.
P83	1	I/O	Port 83: I/O port (with pull-up resistor).
TO5		Output	Timer output 5: Timer 4 output pin.

Table 2.2.2	Names and	Functions	in l	MCU	Mode	(2/4)
	Names and	1 unotions		100	Mouc	(4/7)

Pin names	Number of pins	I/O	Functions
P84	1	I/O	Port 84: I/O port (with pull-up resistor).
TI6		Input	Timer input 6: Timer 5 count/capture trigger signal input.
INT6		Input	Interrupt request pin 6: Interrupt request pin with programmable rising/falling edge.
P85	1	I/O	Port 85: I/O port (with pull-up resistor).
TI7		Input	Timer input 7: Timer 5 count/capture trigger signal input.
INT7		Input	Interrupt request pin 7: Interrupt request pin with rising edge.
P86	1	I/O	Port 86: I/O port (with pull-up resistor).
TO6		Output	Timer output 6: Timer 5 output pin.
P87	1	I/O	Port 87: I/O port (with pull-up resistor).
INT0		Input	Interrupt request pin 0: Interrupt request pin with programmable level/rising edge.
P90	1	I/O	Port 90: I/O port (with pull-up resistor).
TXD0		Output	Serial send data 0.
P91	1	I/O	Port 91: I/O port (with pull-up resistor).
RXD0		Input	Serial receive data 0.
P92	1	I/O	Port 92: I/O port (with pull-up resistor).
CTS0		Input	Serial data send enable 0 (Clear to send).
SCLK0		I/O	Serial clock I/O 0.
P93	1	I/O	Port 93: I/O port (with pull-up resistor).
TXD1		Output	Serial send data 1.
P94	1	I/O	Port 94: I/O port (with pull-up resistor).
RXD1		Input	Serial receive data 1.
P95	1	I/O	Port 95: I/O port (with pull-up resistor).
SCLK1		I/O	Serial clock I/O 1.
PA0 to PA6	7	I/O	Port A: I/O ports.
PA7	1	I/O	Port A7: I/O port.
SCOUT		Output	System clock output: Outputs system clock or 1/2 oscillation clock for synchronizing to external circuit.
WDTOUT	1	Output	Watchdog timer output pin.
NMI	1	Input	Non-maskable interrupt request pin: Interrupt request pin with falling edge. Can also be operated at rising edge by program.
CLK	1	Output	Clock output: Outputs "system clock ÷ 2" clock. Pulled-up during reset. Can be set to output disable for reducing noise.
ĒĀ	1	Input	External access: "1" should be inputted with TMP93PW40.

Table 2.2.3	Names and	Functions ir	n MCU	Mode	(3/4)
10010 2.2.0	riunico una		11000	mouo	(0, 1)

Pin Names	Number of Pins	I/O	Functions	
AM8/ AM16	1	Input	Address mode: Selects external data bus width. "1" should be inputted. The data bus width for external access is set by chip select/wait control register, port 1 control register.	
ALE	1	Output	Address latch enable Can be set to output disable for reducing noise.	
RESET	1	Input	Reset: Initializes LSI. (with pull-up resistor)	
X1/X2	2	Input/Output	put High-frequency oscillator connecting pin.	
XT1	1	Input	Low-frequency oscillator connecting pin.	
P96		I/O	Port 96: I/O port (open-drain output).	
XT2	1	Output	Low-frequency oscillator connecting pin.	
P97		I/O	Port 97: I/O port (open-drain output).	
TEST1/TEST2	2	Output/Input	TEST1 should be connected with TEST2 pin. Do not connect to any other pins.	
VCC	3		Power supply pin.	
VSS	3		GND pin (0 V).	
AVCC	1		Power supply pin for AD converter.	
AVSS	1		GND pin for AD converter (0 V).	

Table 2.2.4 Names and Functions in MCU Mode (4/4)

Note: Pull-up/pull-down resistor can be released from the pin by software (except RESET pin).

(2) PROM mode

Table 2.2.5 Names and Functions of PROM Mode	9
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Pin Function	Pin Number	Input/ Output	Function	Pin Name (MCU Mode)		
A7 to A0	8	Input		P27 to P20		
A15 to A8	8	Input	Memory address of program	P17 to P10		
A16	1	Input		P33		
D7 to D0	8	I/O	Memory data of program	P07 to P00		
CE	1	Input	Chip enable	P32		
ŌĒ	1	Input	Output control	P30		
PGM	1	Input	Program control	P31		
VPP	1	Power supply	12.75 V/5 V (Power supply of program)	ĒĀ		
VCC	4	Power supply	6.25 V/5 V	VCC, AVCC		
VSS	4	Power supply	0 V	VSS, AVSS		
Pin Function	Pin Number	Input/ Output	Disposal of Pin			
P34	1	Input	Fix to low level (security pin)			
RESET	1	Input	Firsts law lavel (DDOM mede)			
CLK	1	Input	Fix to low level (PROM mode)			
ALE	1	Output	Open			
X1	1	Input	Crystal			
X2	1	Output	Crystal			
P42 to P40 P37 to P35 AM8/ AM16	7	Input	Fix to high level			
TEST1, TEST2	2	Input/ Output	TEST1 should be connected with TEST2 Do not connect to any other pins.	pin.		
P57 to P50 P67 to P60 P73 to P70 P87 to P80 P97 to P90 PA7 to PA0 VREFH VREFL NMI WDTOUT	48	I/O	Open			

3. Operation

This section describes in blocks the functions and basic operations of TMP93PW40.

The TMP93PW40 has ROM in place of the mask ROM which is included in the TMP93CW40. The other configuration and functions are the same as the TMP93CW40. Regarding the function of the TMP93PW40, which is not described herein, see the TMP93CW40.

The TMP93PW40 has two operational modes: MCU mode and PROM mode.

3.1 MCU Mode

(1) Mode setting and function

The MCU mode is set by opening the CLK pin (Output status). In the MCU mode, the operation is same as TMP93CW40.

3.2 Memory Map

Figure 3.2.1 are memory map of the TMP93PW40.

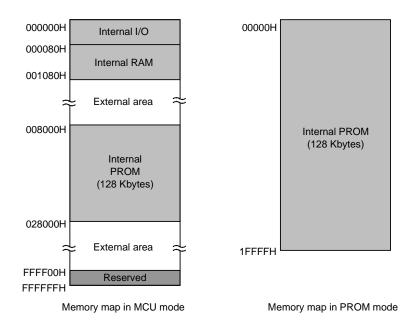


Figure 3.2.1 Memory Map

3.3 PROM Mode

(1) Mode setting and function

PROM mode is set by setting the $\overline{\text{RESET}}$ and CLK pins to the "L" level. The programming and verification for the internal PROM is achieved by using a general PROM programmer with the adaptor socket.

a. OTP adaptor

BM11129: TMP93PS40DF, TMP93PW40DF adaptors

b. Setting OTP adaptor

Set the switch (SW1) to N side.

- c. Setting PROM programmer
 - i) Set PROM type to TC571000D.

Size: 1 Mbits (128 K \times 8 bits)

VPP: 12.75 V

tpw: 100 μs

The electric signature mode (Hereinafter referred to as "signature".) is not supported. Therefore if signature is used, the device is damaged because 12.75 V is applied to A9 of address. Do not use signature.

ii) Transferring the data (copy)

In TMP93PW40, PROM is placed on addresses 00000 to 1FFFFH in PROM mode, and addresses 08000H to 27FFFH in MCU mode. Therefore data should be transferred to addresses 00000 to 1FFFFH in PROM mode using the object converter (tuconv) or the block transfer mode (see instruction manual of PROM programmer.) or making the object data.

iii) Setting the programming address

Start address: 00000H End address: 1FFFFH d. Programming

Program/verify according to the procedures of PROM programmer.

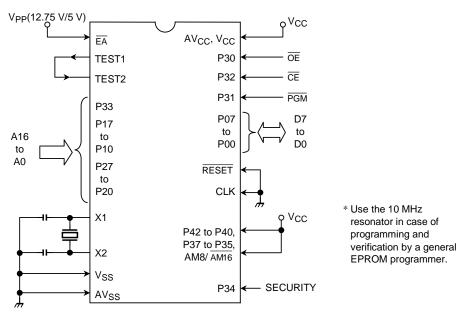


Figure 3.3.1 PROM Mode Pin Setting

(2) Programming flow chart

The programming mode is set by applying 12.75 V (programming voltage) to the VPP pin when the following pins are set as follows,

(VCC: $6.25 \text{ V}, \overline{\text{RESET}}$: "L" level, CLK: "L" level).

While address and data are fixed and \overline{CE} pin is set to "L" level, 0.1 ms of "L" level pulse is applied to \overline{PGM} pin to program the data.

Then the data in the address is verified.

If the programmed data is incorrect, another 0.1 ms pulse is applied to $\overline{\text{PGM}}\,$ pin.

This programming procedure is repeated until correct data is read from the address. (25 times maximum)

Subsequently, all data are programmed in all addresses.

The verification for all data is done under the condition of $V_{PP} = V_{CC} = 5$ V after all data were written.

Figure 3.3.2 shows the programming flow chart.

High Speed Program Writing

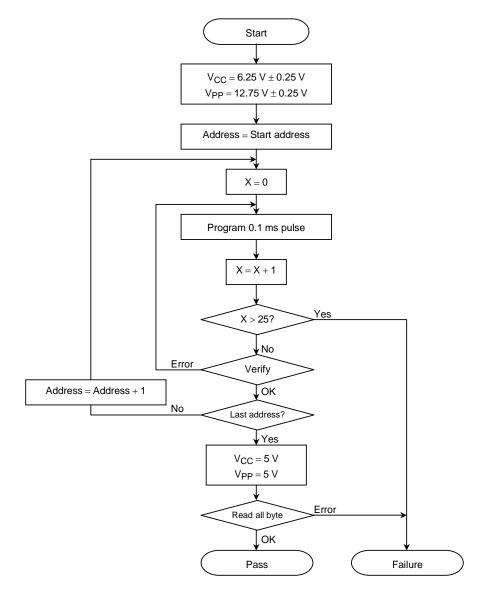


Figure 3.3.2 Flow Chart

(3) Security bit

The TMP93PW40 has a security bit.

If the security bit is programmed to "0", the content of the PROM can not be read in PROM mode.

(Outputs data FFH)

How to program the security bit.

The difference from the programming procedures described in section 3.3(1) are follows.

a. Setting OTP adapter

Set the switch (SW1) to S side.

- b. Setting PROM programmer
 - ii) Transferring the data
 - iii) Setting programming address

The security bit is in bit 0 of address 00000H.

Set the start address 00000H and the end address 00000H.

Set the data FEH at the address 00000H.

40 to 0500

-

4. Electrical Characteristics

4.1 Maximum Ratings (TMP93PW40DF)

"X" used in an expression shows a frequency of clock fFPH selected by SYSCR1<SYSCK>. If a clock gear or a low speed oscillator is selected, a value of "X" is different. The value in an example is calculated at fc, gear = 1/fc (SYSCR1 < SYSCK, GEAR2:0 > = "0000").

Parameter	Symbol	Rating	Unit
Power supply voltage	V _{CC}	-0.5 to 6.5	V
Input voltage	V _{IN}	-0.5 to V _{CC} + 0.5	V
Output current (total)	ΣΙΟΓ	120	mA
Output current (total)	ΣI_{OH}	-80	mA
Power dissipation (Ta = 85°C)	PD	600	mW
Soldering temperature (10 s)	T _{SOLDER}	260	°C
Storage temperature	T _{STG}	-65 to 150	°C
Operating temperature	T _{OPR}	-40 to 85	°C

Note: The maximum ratings are rated values which must not be exceeded during operation, even for an instant. Any one of the ratings must not be exceeded. If any maximum rating is exceeded, a device may break down or its performance may be degraded, causing it to catch fire or explode resulting in injury to the user. Thus, when designing products which include this device, ensure that no maximum rating value will ever be exceeded.

		1					1a = -4	0 to 85°C
	Parameter	Symbol	Conditio	n	Min	Typ. (Note)	Max	Unit
Pow	er supply voltage		fc = 4 to 20 MHz	fs = 30 to	4.5			
	$ \begin{pmatrix} AV_{CC} = V_{CC} \\ AV_{CC} = V_{SS} = 0 \end{pmatrix} $	V _{CC}	fc = 4 to 12.5 MHz	34 kHz	2.7	-	5.5	V
		N	$V_{CC} \ge 4.5 V$				0.8	
Input low voltage	AD0 to AD15	VIL	$V_{CC} < 4.5 V$				0.6	
	Port 2 to port A (except P87)	V _{IL1}			-0.3		0.3 V _{CC}	
	RESET, NMI, INTO	V _{IL2}	$V_{CC} = 2.7$ to 5.5 V				0.25 V _{CC}	
	EA , AM8/ AM16	V _{IL3}					0.3	
	X1	V _{IL4}					0.2 V _{CC}	V
0	AD0 to AD15	VIH	$V_{CC} \ge 4.5 \text{ V}$		2.2		L .	v
tage		VIН	$V_{CC} < 4.5 V$		2.0		V _{CC} + 0.3	
Input high voltage	Port 2 to port A (except P87)	VIH1			0.7 V _{CC}			
ut hi	RESET, NMI, INTO	V _{IH2}	$V_{CC}{=}2.7$ to 5.5 V		0.75 V _{CC}			
Inpu	EA, AM8/ AM16	V _{IH3}			$V_{CC} - 0.3$			
	X1	V _{IH4}			0.8 V _{CC}			
Outp	out low voltage	V _{OL}	$I_{OL} = 1.6 \text{ mA}$ (V _{CC} = 2.7 t	o 5.5 V)			0.45	
Outr	but high voltage	V _{OH1}	$I_{OH} = -400 \ \mu A$ (V _{CC} = 3	s V ± 10%)	2.4			V
Ծակ	ou nign voitage	V _{OH2}	$I_{OH} = -400 \ \mu A$ (V _{CC} = 5	V ± 10%)	4.2			

4.2 DC Characteristics (1/2)

Note: Typical values are for $Ta = 25^{\circ}C$ and $V_{CC} = 5$ V unless otherwise noted.

4.2 DC Characteristics (2/2)

Parameter	Symbol	Condition	Min	Typ. (Note 1)	Max	Unit
Darlington drive current (8 output pins max)	I _{DAR} (Note 2)	$V_{EXT} = 1.5 \text{ V}$ $R_{EXT} = 1.1 \text{ k}\Omega$ (when $V_{CC} = 5 \text{ V} \pm 10\%$)	-1.0		-3.5	mA
Input leakage current	ILI	$0.0 \leq V_{IN} \leq V_{CC}$		0.02	±5	μA
Output leakage current	ILO	$0.2 \leq V_{IN} \leq V_{CC} - 0.2$		0.05	±10	μΛ
Powerdown voltage (at STOP, RAM back-up)	V _{STOP}	$\label{eq:VIL2} \begin{array}{l} V_{IL2} = 0.2 \ V_{CC}, \\ V_{IH2} = 0.8 \ V_{CC} \end{array}$	2.0		6.0	V
RESET pull-up resistor	Page	$V_{CC}=5~V\pm10\%$	50		150	kΩ
RESET pull-up resistor	R _{RST}	$V_{CC}=3~V\pm10\%$	80		200	K52
Pin capacitance	C _{IO}	fc = 1 MHz			10	pF
Schmitt width RESET,MII,INT0	V _{TH}		0.4	1.0		V
Programmable	R _{KL}	$V_{CC}=5~V\pm10\%$	10		80	
pull-down resistor	r KL	$V_{CC}=3~V\pm10\%$	30		150	kΩ
Programmable	R _{KH}	$V_{CC}=5~V\pm10\%$	50		150	K22
pull-up resistor	INKH	$V_{CC}=3~V\pm10\%$	100		300	
NORMAL (Note 3)		$V_{CC}=5~V\pm10\%$		19	25	
NORMAL2 (Note 4)		fc = 20 MHz		24	30	
RUN				17	25	mA
IDLE2				10	15	
IDLE1				3.5	5	
NORMAL (Note 3)		$V_{CC}=3~V\pm10\%$		6.5	10	
NORMAL2 (Note 4)		fc = 12.5 MHz		9.5	13	
RUN		$(Typ. : V_{CC} = 3.0 V)$		5.0	9	mA
IDLE2	Icc			3.0	5	
IDLE1				0.8	1.5]
SLOW (Note 3)		$V_{CC}=3~V\pm10\%$		20	45	
RUN		fs = 32.768 kHz		16	40	
IDLE2		(Typ. :V _{CC} = 3.0 V)		10	30	μΑ
IDLE1				5	25]
		Ta ≤ 50°C			10	
STOP		Ta ≤ 70°C		0.2	20	μA
		Ta ≤ 85°C			50	

Note 1: Typical values are for Ta = 25°C and V_{CC} = 5 V unless otherwise noted.

Note 2: I_{DAR} is guranteed for total of up to 8 ports.

Note 3: The condition of measurement of I_{CC} (NORMAL/SLOW).

Only CPU operates. Output ports are open and Input ports fixed.

Note 4: The condition of measurement of I_{CC} (NORMAL 2).

CPU and all peripherals operate. Output ports are open and input ports fixed.

4.3 AC Characteristics

(1) $V_{CC} = 5 V \pm 10\%$

No.	Parameter	Symbol	Vari	able	16 I	ИНz	20	MHz	Unit
NO.	i arameter	Symbol	Min	Max	Min	Max	Min	Max	Onit
1	Osc. period (= x)	tosc	50	31250	62.5		50		ns
2	CLK pulse width	t _{CLK}	2x - 40		85		60		ns
3	A0 to A23 valid \rightarrow CLK hold	t _{AK}	0.5x – 20		11		5		ns
4	CLK valid \rightarrow A0 to A23 hold	t _{KA}	1.5x – 70		24		5		ns
5	A0 to A15 valid \rightarrow ALE fall	t _{AL}	0.5x – 15		16		10		ns
6	ALE fall \rightarrow A0 to A15 hold	t _{LA}	0.5x – 20		11		5		ns
7	ALE high pulse width	t _{LL}	x - 40		23		10		ns
8	ALE fall $\rightarrow \overline{RD} / \overline{WR}$ fall	t _{LC}	0.5x – 25		6		0		ns
9	\overline{RD} / \overline{WR} rise \rightarrow ALE rise	t _{CL}	0.5x – 20		11		5		ns
10	A0 to A15 valid $\rightarrow \overline{RD} / \overline{WR}$ fall	t _{ACL}	x – 25		38		25		ns
11	A0 to A23 valid $\rightarrow \overline{\text{RD}} / \overline{\text{WR}}$ fall	t _{ACH}	1.5x – 50		44		25		ns
12	$\overline{\text{RD}}$ / $\overline{\text{WR}}~\text{rise} \rightarrow \text{A0}$ to A23 hold	t _{CA}	0.5x – 25		6		0		ns
13	A0 to A15 valid \rightarrow D0 to D15 input	t _{ADL}		3.0x - 55		133		95	ns
14	A0 to A23 valid \rightarrow D0 to D15 input	t _{ADH}		3.5x - 65		154		110	ns
15	$\overline{\text{RD}}$ fall \rightarrow D0 to D15 input	t _{RD}		2.0x - 60		65		40	ns
16	RD low pulse width	t _{RR}	2.0x - 40		85		60		ns
17	$\overline{\text{RD}}$ rise \rightarrow D0 to D15 hold	t _{HR}	0		0		0		ns
18	$\overline{\text{RD}}$ rise \rightarrow A0 to A15 output	t _{RAE}	x – 15		48		35		ns
19	WR low pulse width	t _{WW}	2.0x - 40		85		60		ns
20	D0 to D15 valid $\rightarrow \overline{\text{WR}}$ rise	t _{DW}	2.0x – 55		70		45		ns
21	$\overline{\text{WR}}~\text{rise} \rightarrow \text{D0}~\text{to}~\text{D15}~\text{hold}$	t _{WD}	0.5x – 15		16		10		ns
22	A0 to A23 valid $\rightarrow \overline{\text{WAIT}}$ input $\begin{pmatrix} (1 + N) \text{ WAIT} \\ \text{mode} \end{pmatrix}$	t _{AWH}		3.5x - 90		129		85	ns
23	A0 to A15 valid $\rightarrow \overline{\text{WAIT}}$ input $\begin{pmatrix} (1 + N) \text{ WAIT} \\ \text{mode} \end{pmatrix}$	t _{AWL}		3.0x - 80		108		70	ns
24	$\overline{\text{RD}} / \overline{\text{WR}} \text{ fall} \to \overline{\text{WAIT}} \text{ hold } \qquad \left[\begin{pmatrix} (1 + N) \text{WAIT} \\ \text{mode} \end{pmatrix} \right]$	t _{CW}	2.0x + 0		125		100		ns
25	A0 to A23 valid \rightarrow Port input	t _{APH}		2.5x - 120		36		5	ns
26	A0 to A23 valid \rightarrow Port hold	t _{APH2}	2.5x + 50		206		175		ns
27	\overline{WR} rise \rightarrow Port valid	t _{CP}		200		200		200	ns
28	A0 to A23 valid $\rightarrow \overline{RAS}$ fall	t _{ASRH}	1.0x – 40		23		10		ns
29	A0 to A15 valid $\rightarrow \overline{RAS}$ fall	t _{ASRL}	0.5x – 15		16		10		ns
30	\overline{RAS} fall \rightarrow D0 to D15 input	t _{RAC}		2.5x - 70		86		55	ns
31	\overline{RAS} fall \rightarrow A0 to A15 hold	t _{RAH}	0.5x – 15		16		10		ns
32	RAS low pulse width	t _{RAS}	2.0x - 40		85		60		ns
33	RAS high pulse width	t _{RP}	2.0x - 40		85		60		ns
34	$\overline{\text{CAS}}$ fall $\rightarrow \overline{\text{RAS}}$ rise	t _{RSH}	1.0x - 40		23		10		ns
35	\overline{RAS} rise $\rightarrow \overline{CAS}$ rise	t _{RSC}	0.5x – 25		6		0		ns
36	$\overline{\text{RAS}}$ fall $\rightarrow \overline{\text{CAS}}$ fall	t _{RCD}	1.0x - 40		23		10		ns
37	\overline{CAS} fall \rightarrow D0 to D15 input	tCAC		1.5x – 65		29		10	ns
38	CAS low pulse width	t _{CAS}	1.5x – 30		64		40		ns

AC measuring conditions

• Output level: High 2.2 V/Low 0.8 V, $C_L = 50 \text{ pF}$

(However $C_L = 100 \text{ pF}$ for AD0 to AD15, A0 to A23, ALE, \overline{RD} , \overline{WR} , \overline{HWR} , R/\overline{W} , CLK, \overline{RAS} , $\overline{CAS0}$ to $\overline{CAS2}$)

• Input level: High 2.4 V/Low 0.45 V (AD0 to AD15) High 0.8 V_{CC}/Low 0.2 V_{CC} (Except for AD0 to AD15)

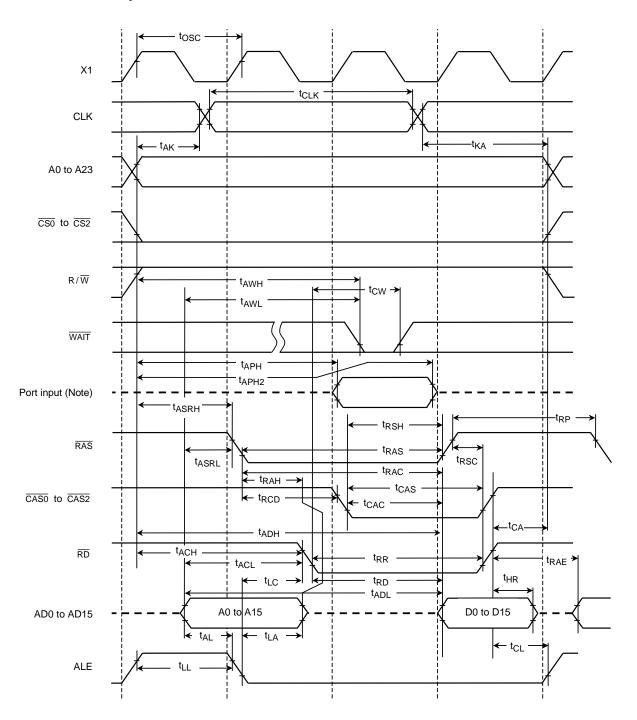
No.	Parameter	Symbol	Vari	able	12.5	MHz	Unit
INO.	Falameter	Symbol	Min	Max	Min	Max	Unit
1	Osc. period (= x)	tosc	80	31250	80		ns
2	CLK pulse width	t _{CLK}	2x - 40		120		ns
3	A0 to A23 valid \rightarrow CLK hold	t _{AK}	0.5x - 30		10		ns
4	CLK valid \rightarrow A0 to A23 hold	t _{KA}	1.5x – 80		40		ns
5	A0 to A15 valid \rightarrow ALE fall	t _{AL}	0.5x - 35		5		ns
6	ALE fall \rightarrow A0 to A15 hold	t _{LA}	0.5x - 35		5		ns
7	ALE high pulse width	t _{LL}	x - 60		20		ns
8	ALE fall $\rightarrow \overline{RD} / \overline{WR}$ fall	tLC	0.5x - 35		5		ns
9	\overline{RD} / \overline{WR} rise $\rightarrow ALE$ rise	t _{CL}	0.5x - 40		0		ns
10	A0 to A15 valid $\rightarrow \overline{RD} / \overline{WR}$ fall	t _{ACL}	x – 50		30		ns
11	A0 to A23 valid $\rightarrow \overline{RD} / \overline{WR}$ fall	t _{ACH}	1.5x – 50		70		ns
12	$\overline{\text{RD}}$ / $\overline{\text{WR}}$ rise \rightarrow A0 to A23 hold	t _{CA}	0.5x - 40		0		ns
13	A0 to A15 valid \rightarrow D0 to D15 input	t _{ADL}		3.0x - 110		130	ns
14	A0 to A23 valid \rightarrow D0 to D15 input	t _{ADH}		3.5x – 125		155	ns
15	$\overline{\text{RD}}$ fall \rightarrow D0 to D15 input	t _{RD}		2.0x - 115		45	ns
16	RD low pulse width	t _{RR}	2.0x - 40		120		ns
17	$\overline{\text{RD}}$ rise \rightarrow D0 to D15 hold	t _{HR}	0		0		ns
18	$\overline{\text{RD}}$ rise \rightarrow A0 to A15 output	t _{RAE}	x – 25		55		ns
19	WR low pulse width	t _{WW}	2.0x - 40		120		ns
20	D0 to D15 valid $\rightarrow \overline{WR}$ rise	t _{DW}	2.0x - 120		40		ns
21	$\overline{\text{WR}}$ rise \rightarrow D0 to D15 hold	t _{WD}	0.5x - 40		0		ns
22	A0 to A23 valid $\rightarrow \overline{\text{WAIT}}$ input $\begin{pmatrix} (1+N) \text{ WAIT} \\ \text{mode} \end{pmatrix}$	t _{AWH}		3.5x – 130		150	ns
23	A0 to A15 valid $\rightarrow \overline{\text{WAIT}}$ input $\begin{pmatrix} (1+N) \text{ WAIT} \\ \text{mode} \end{pmatrix}$	t _{AWL}		3.0x - 100		140	ns
24	$\overline{RD} / \overline{WR} \; \; fall \to \overline{WAIT} \; \; hold \qquad \begin{bmatrix} (1 + N) WAIT \\ mode \end{bmatrix}$	t _{CW}	2.0x + 0		160		ns
25	A0 to A23 valid \rightarrow Port input	t _{APH}		2.5x - 195		5	ns
26	A0 to A23 valid \rightarrow Port hold	t _{APH2}	2.5x + 50		250		ns
27	\overline{WR} rise \rightarrow Port valid	t _{CP}		200		200	ns
28	A0 to A23 valid $\rightarrow \overline{RAS}$ fall	t _{ASRH}	1.0x - 60		20		ns
29	A0 to A15 valid $\rightarrow \overline{RAS}$ fall	t _{ASRL}	0.5x - 40		0		ns
30	\overline{RAS} fall \rightarrow D0 to D15 input	t _{RAC}		2.5x - 90		110	ns
31	$\overline{\text{RAS}}$ fall \rightarrow A0 to A15 hold	t _{RAH}	0.5x – 25		15		ns
32	RAS low pulse width	t _{RAS}	2.0x - 40		120		ns
33	RAS high pulse width	t _{RP}	2.0x - 40		120		ns
34	$\overline{\text{CAS}}$ fall $\rightarrow \overline{\text{RAS}}$ rise	t _{RSH}	1.0x – 55		25		ns
35	\overline{RAS} rise $\rightarrow \overline{CAS}$ rise	t _{RSC}	0.5x – 25		15		ns
36	\overline{RAS} fall $\rightarrow \overline{CAS}$ fall	t _{RCD}	1.0x - 40		40		ns
37	\overline{CAS} fall \rightarrow D0 to D15 input	tCAC		1.5x – 120		0	ns
38	CAS low pulse width	tCAS	1.5x – 40		80		ns

(2) $V_{CC} = 3 V \pm 10\%$

AC measuring conditions

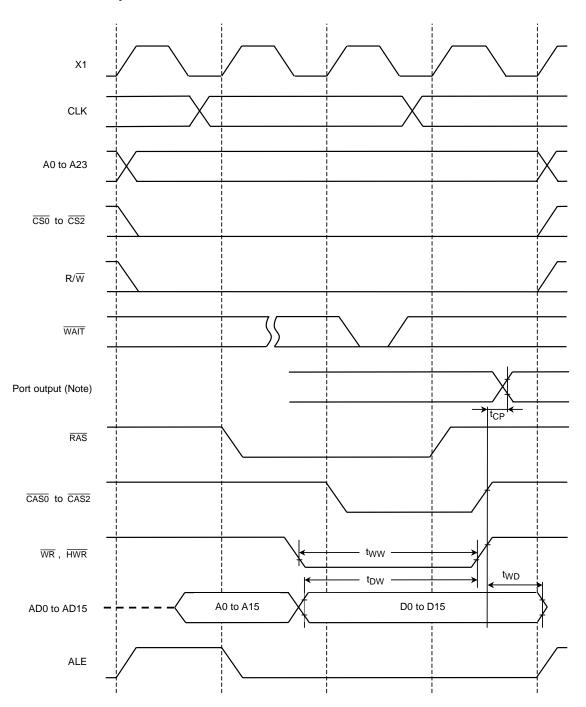
- Output level: High $0.7 \times VCC/Low 0.3 \times VCC$, CL = 50 pF
- Input level: High $0.9 \times V_{CC}/Low 0.1 \times V_{CC}$

(1) Read cycle



Note: Since the CPU accesses the internal area to read data from a port, the control signals of external pins such as RD and CS are not enabled. Therefore, the above waveform diagram should be regarded as depicting internal operation. Please also note that the timing and AC characteristics of port input/output shown above are typical representation. For details, contact your local Toshiba sales representative.

(2) Write cycle



Note: Since the CPU accesses the internal area to write data to a port, the control signals of external pins such as \overline{WR} and \overline{CS} are not enabled. Therefore, the above waveform diagram should be regarded as depicting internal operation. Please also note that the timing and AC characteristics of port input/output shown above are typical representation. For details, contact your local Toshiba sales representative.

4.4 AD Conversion Characteristics

					$AV_{CC} = V_{CC}, AV$	V _{SS} = V _{SS}
Parameter	Symbol	Power Supply	Min	Тур.	Max	Unit
Analog reference voltage (+)	V _{REFH}	$V_{CC}=5~V\pm10\%$	V _{CC} – 1.5 V	V _{CC}	V _{CC}	
Analog reference voltage (+)	VREFH	$V_{CC}=3~V\pm10\%$	$V_{CC} - 0.2 V$	V _{CC}	V _{CC}	
Analog reference voltage (-)	\/	$V_{CC}=5~V\pm10\%$	V _{SS}	V _{SS}	V_{SS} + 0.2 V	V
Analog reference voltage (-)	V _{REFL}	$V_{CC}=3~V\pm10\%$	V _{SS}	V _{SS}	V_{SS} + 0.2 V	
Analog input voltage range	V _{AIN}		V _{REFL}		V _{REFH}	
Analog current for analog reference voltage	1	$V_{CC}=5~V\pm10\%$		0.5	1.5	mA
<vrefon> = 1</vrefon>	I _{REF} (V _{REFL} = 0 V)	$V_{CC}=3~V\pm10\%$		0.3	0.9	mA
<vrefon> = 0</vrefon>	(*REFL = \$ *)	V_{CC} = 2.7 to 5.5 V		0.02	5.0	μA
Error (excluding quantizing		$V_{CC}=5~V\pm10\%$		±1.0	±3.0	LSB
error)	_	$V_{CC}=3~V\pm10\%$		±1.0	±3.0	LOD

Note 1: 1LSB = $(V_{REFH} - V_{REFL}) / 2^{10} [V]$

Note 2: Minimum operation frequency

The operation of the AD converter is guaranteed only when fc (high-frequency oscillator) is used. (It is not guaranteed when fs is used.) Additionally, it is guaranteed with 4 MHz or more.

Note 3: The value I_{CC} includes the current which flows through the AV_{CC} pin.

4.5 Serial Channel Timing

(1) I/O interface mode

a. SCLK input mode

Parameter	Symbol	Variable		32.768 kHz (Note 1)		12.5 MHz		20 MHz		Unit
		Min	Max	Min	Max	Min	Max	Min	Max	
SCLK cycle	tSCY	16X		488 μs		1280		800		ns
Output data → Rising edge or falling edge (Note 2) of SCLK	toss	t _{SCY} /2 - 5X - 50		91.5 µs		190		100		ns
SCLK rising edge or falling edge (Note 2) \rightarrow Output data hold	tons	5X – 100		152 μs		300		150		ns
SCLK rising edge or falling edge (Note 2) \rightarrow Input data hold	^t HSR	0		0		0		0		ns
SCLK rising edge or falling edge (Note 2) \rightarrow Effective data input	^t SRD		t _{SCY} – 5X – 100		336 µs		780		450	ns

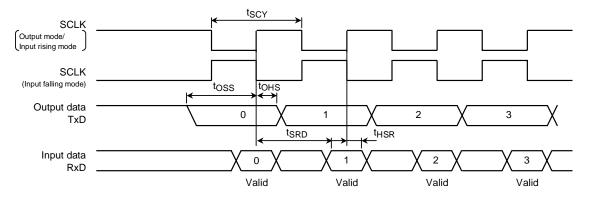
Note 1: When fs is used as system clock (f_{SYS}) or fs is used as input clock to prescaler.

Note 2: SCLK rising/falling timing ... SCLK rising in the rising mode of SCLK, SCLK falling in the falling mode of SCLK.

Parameter	Symbol		able	32.768 (No		12.5	MHz	20 1	MHz	Unit
		Min	Max	Min	Мах	Min	Max	Min	Мах	
SCLK cycle (programmable)	tSCY	16X	8192X	488	250 ms	1.28	655.36	0.8	409.6	μS
Output data \rightarrow SCLK rising edge	toss	t _{SCY} - 2X - 150		427 μs		970		550		ns
SCLK rising edge \rightarrow Output data hold	tOHS	2X - 80		60 µs		80		20		ns
SCLK rising edge \rightarrow Input data hold	t _{HSR}	0		0		0		0		ns
SCLK rising edge \rightarrow Effective data input	tSRD		t _{SCY} - 2X - 150		428 μs		970		550	ns

b. SCLK output mode

Note: When fs is used as system clock (f_{SYS}) or fs is used as input clock to prescaler.



4.6 Timer/Counter Input Clock (TI0, TI4, TI5, TI6 and TI7)	4.6	Timer/Counter	Input Clock	(TI0, TI4,	TI5, TI6 ai	nd TI7)
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Parameter	Cumphiel		able	12.5	MHz	20 1	MHz	Unit
Parameter	Symbol	Min	Max	Min	Max	Min	Max	Offic
Clock cycle	t _{VCK}	8X + 100		740		500		ns
Low level clock pulse width	t _{VCKL}	4X + 40		360		240		ns
High level clock pulse width	t _{VCKH}	4X + 40		360		240		ns

4.7 Interrupt and Capture

(1) $\overline{\text{NMI}}$ and INT0 interrupts

Parameter	Cumhal	Vari	Variable		MHz	20 N	MHz	Unit
Parameter	Symbol	Min	Max	Min	Max	Min	Max	Offic
$\overline{\rm NMI}$, INT0 low level pulse width	t _{INTAL}	4X		320		200		ns
$\overline{\rm NMI}$, INT0 high level pulse width	t _{INTAH}	4X		320		200		ns

(2) INT4 to 7 interrupts and capture

Input pulse width of INT4 to 7 depends on the operation clock of CPU and Timer (9 bit prescaler). The following shows the pulse width in each clock.

System Clock	Prescaler Clock	t _{INTBL} (INT4 to 7 lo	w-level pulse width)	t _{INTBH} (INT4 to 7 hi	gh-level pulse width)	
Selected	Selected	Variable	20 MHz	Variable	20 MHz	Unit
<sysck></sysck>	<prck1:0></prck1:0>	Min	Min	Min	Min	
	00 (f _{FPH})	8X + 100	500	8X + 100	500	ns
0 (fc)	01 (fs)	8XT + 0.1	244.3	8XT + 0.1	244.3	
	10 (fc/16)	128X + 0.1	6.5	128X + 0.1	6.5	
1 (fs)	00 (f _{FPH})	8XT + 0.1	244.3	8XT + 0.1	244.3	μS
(Note 2)	01 (fs)	071 + 0.1	244.5	0/1 + 0.1	244.5	

Note 1: XT represents the cycle of the low frequency clock fs. Calculated at fs = 32.768 kHz.

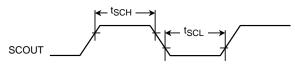
Note 2: When fs is used as the system clock, fc/16 can not be selected for the prescaler clock.

4.8 SCOUT Pin AC Characteristics

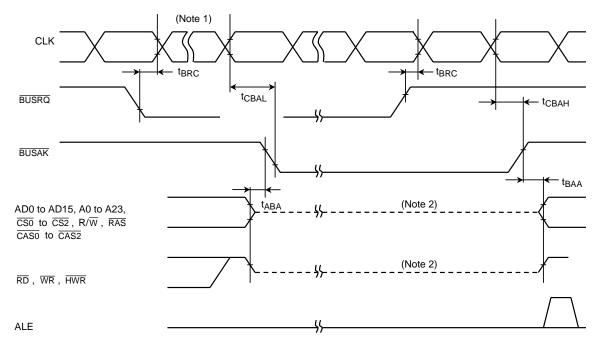
Boro	meter		Variable		12.5 MHz		20 MHz		Unit
Fala	inetei	Symbol	Min	Max	Min	Max	Min	Max	Unit
High-level pulse	$V_{CC}=5~V\pm10\%$	taau	0.5X – 10		30		15		ns
width	$V_{CC}=3~V\pm10\%$	tSCH	0.5X – 20		20		-	-	115
Low-level pulse	$V_{CC}=5~V\pm10\%$	t	0.5X – 10		30		15		ns
width	$V_{CC}=3~V\pm10\%$	t _{SCL}	0.5X – 20		20		-	-	115

Measurement condition

• Output level: High 2.2 V/Low 0.8 V, $C_L = 10 \text{ pF}$







Parameter	Symbol	Variable		12.5	12.5 MHz		20 MHz	
i arameter	Symbol	Min	Max	Min	Max	Min	Max	Unit
BUSRQ set-up time to CLK	t _{BRC}	120		120		120		ns
$CLK \rightarrow \overline{BUSAK}$ falling edge	t _{CBAL}		1.5x + 120		240		195	ns
$CLK \rightarrow \overline{BUSAK}$ rising edge	t _{CBAH}		0.5x + 40		80		65	ns
Output Buffer off to BUSAK	t _{ABA}	0	80	0	80	0	80	ns
BUSAK to Output Buffer on	t _{BAA}	0	80	0	80	0	80	ns

Note 1: The Bus will be released after the WAIT request is inactive, when the BUSRQ is set to "0" during "Wait" cycle.

Note 2: This line only shows the output buffer is off-state.

It doesn't indicate the signal level is fixed.

Just after the bus is released, the signal level which is set before the bus is released is kept dynamically by the external capacitance. Therefore, to fix the signal level by an external resistor during bus releasing, designing is executed carefully because the level-fix will be delayed. The internal programmable pull-up/pull-down resistor is switched active/non-active by an internal signal.

4.10 Read Operation in PROM Mode

DC/AC characteristics

			Ta =	$25 \pm 5^{\circ}$ C, V _{CC} = 5	V ± 10%
Parameter	Symbol	Condition	Min	Max	Unit
V _{PP} read voltage	V _{PP}	-	4.5	5.5	V
Input high voltage (A0 to A16, \overline{CE} , \overline{OE} , \overline{PGM})	V _{IH1}	_	2.2	V _{CC} + 0.3	V
Input low voltage (A0 to A16, CE, OE, PGM)	V _{IL1}	_	-0.3	0.8	V
Address to output delay	V _{ACC}	$C_L = 50 \text{ pF}$	-	$2.25T_{CYC} + \alpha$	ns

 $\begin{array}{l} T_{CYC} = 400 \text{ ns (10 MHz clock)} \\ \alpha = 200 \text{ ns} \end{array}$

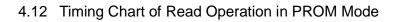
4.11 Program Operation in PROM Mode

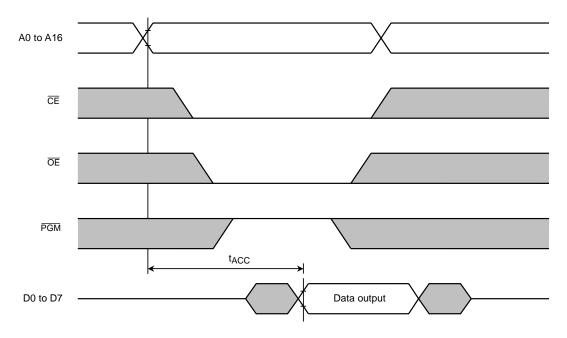
DC/AC characteristics

				$1a = 25 \pm 5$ C, VCC = 0.25 V ± 0.25 V			
Parameter	Symbol	Condition	Min	Тур.	Max	Unit	
Programming supply voltage	V _{PP}	_	12.50	12.75	13.00	V	
Input high voltage (D0 to D7, A0 to A16, $\overline{\text{CE}}$, $\overline{\text{OE}}$, $\overline{\text{PGM}}$)	VIH	-	2.6		$V_{CC} + 0.3$	V	
Input low voltage (D0 to D7, A0 to A16, \overline{CE} , \overline{OE} , \overline{PGM})	VIL	-	-0.3		0.8	V	
V _{CC} supply current	Icc	fc = 10 MHz	-		50	mA	
VPP supply current	IPP	$V_{PP} = 13.00 \text{ V}$	_		50	mA	
PGM program pulse width	t _{PW}	$C_L = 50 \text{ pF}$	0.095	0.1	0.105	ms	

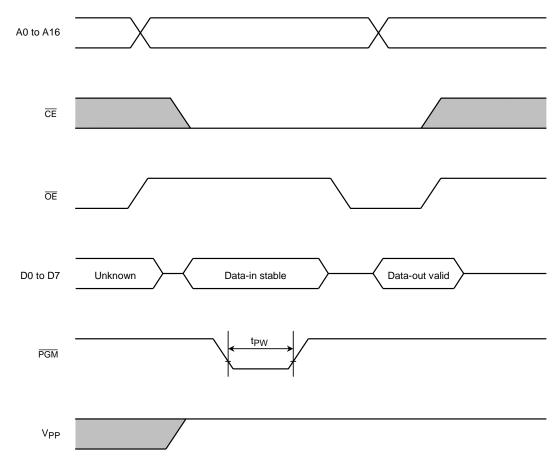
93PW40-24

 $Ta = 25 \pm 5^{\circ}C$. $V_{CC} = 6.25 V \pm 0.25 V$





4.13 Timing Chart of Program Operation in PROM Mode



Note 1: The power supply of V_{PP} (12.75 V) must be turned on at the same time or the later time for a power supply of V_{CC} and must be turned off at the same time or early time for a power supply of V_{CC}.

Note 2: The device suffers a damage taking out and putting in on the condition of $V_{PP} = 12.75$ V.

Note 3: The maximum spec of V_{PP} pin is 14.0 V. Be carefull a overshoot at the programming.

5. Package Dimensions

P-LQFP100-1414-0.50F

Unit: mm

